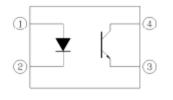
QT BRIGHTEK

4-PIN DC INPUT OPTOCOUPLER

Feature:

- Halogen Free
- High Isolation voltage between input and output (Viso = 5000V rms)
- Creepage distance > 7.62mm
- Operating Temperature up to 100 °C
- Available in Tube or Tape and reel
- Available with standard DIP-4, Wide lead bend, and SMD lead bend options.
- Conventional black housing package

Schematic:



Pin Configuration

- 1. Anode
- 2. Cathode
- 3. Emitter
- 4. Collector

Certification & Compliance:

- Pb free and RoHS Compliant
- UL recognized (File # E338132)
- VDE recognized (File # 40030457)

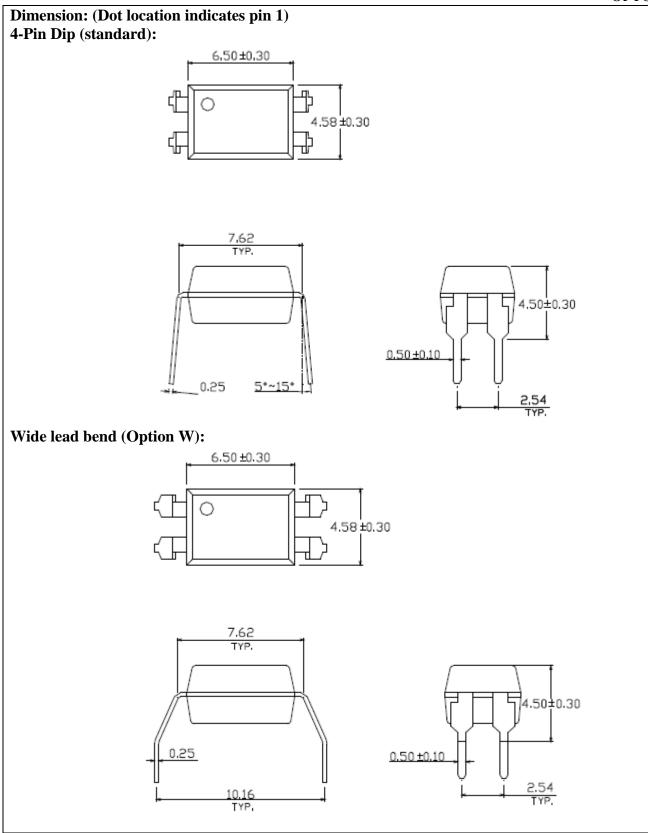


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QT BRIGHTEK

Q817 series

4-PIN DC INPUT OPTOCOUPLER



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QT BRIGHTEK

SMD lead bend (Option S): 6,50±0,30 tÞ 5 0 1,30 4.58±0.30 d, ЦЪ 7.62 TYP. 3 50 ±0.30 4.30 ±0.30 0.6 MIN 0.25 2.54 TYP. 10,30 MAX All Dimensions are in mm Tolerance = +/- 0.1mm

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Absolute Maximum Rating

Symbol	Parameter	Rating	Units
T _{STG}	Storage Temperature	-55 ~ 150	٥C
T _{OPR}	Operating Temperature	-55 ~ 100	°C
T _{SOL}	Lead Solder Temperature	260 for 10 sec	°C
P _{TOT}	Total Power Dissipation	200	mW
EMITTER			
I _F	Continuous Forward Current	50	mA
V _R	Reverse Voltage	6	V
D.	Power Dissipation	70	mW
PD	Power Dissipation Derated above 100°C	2.9	mW/ºC
DETECTOR	8		
V _{CEO}	Collector–Emitter Voltage	80	V
V _{ECO}	Emitter-Collector Voltage	7	V
I _C	Continuous Collector Current	50	mA
Pc	Collector Power Dissipation	150	mW
ГC	Collector Power Dissipation Derated above80 °C	5.8	mW/ºC

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Electrical Characteristic (T_A=25 °C)

Emitter

Symbol	Characteristic	Device Test Condition			Unit		
Symbol	Characteristic	Device		Min	Тур	Max	Onit
V _F	Forward Voltage		$I_F = 20 \text{mA}$	-	1.2	1.4	V
I _R	Reverse Current	Q817	$V_R = 4V$	-	-	10	μA
Ct	Input Capacitance		V = 0, f = 1 kHz	-	30	250	pF

Detector

Symbol	Characteristic	Device	Device Test Condition		Range		
Symbol	Characteristic	Device	Test Condition	Min	Тур	Max	Unit
I _{CEO}	Collector-Emitter Dark current		V _{CE} =20V, I _F =0mA	-	-	100	nA
BV _{CEO}	Collector-Emitter breakdown voltage	Q817	$I_{\rm C} = 0.1 \mathrm{mA}$	80	-	-	V
BV _{ECO}	Emitter-Collector breakdown voltage		I _E = 0.1mA	7	-	-	V

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DC Transfer Characteristic:

		Device	Bin	Test Condition	F	Range		Unit
		Device	DILI	Test Condition	Min	Тур	Max	Offic
			-		50	-	600	
Symbol	Characteristic		Α		80	-	160	
		Q817	В	I _F =5mA, V _{CE} =5V	130	-	260	%
			С		200	-	400	
			D		400	-	600	
	Collector- Emitter			I _F =20mA,		0.1	0.2	V
V _{CE(Sat)}	saturation voltage			I _F =20mA, I _C = 1mA	-	0.1	0.2	V

AC Characteristic

Symbol	Characteristic	Dovice	Bin	Test Condition	F	Range		Unit
Symbol	Characteristic	Device	DILI	Test Condition	Min	Тур	Max	Unit
t _r	Rise time			V _{CE} = 2V, I _C = 2mA	-	6	18	
t _f	Fall time			$R_L = 100\Omega$	-	8	18	μs

Isolation Characteristic

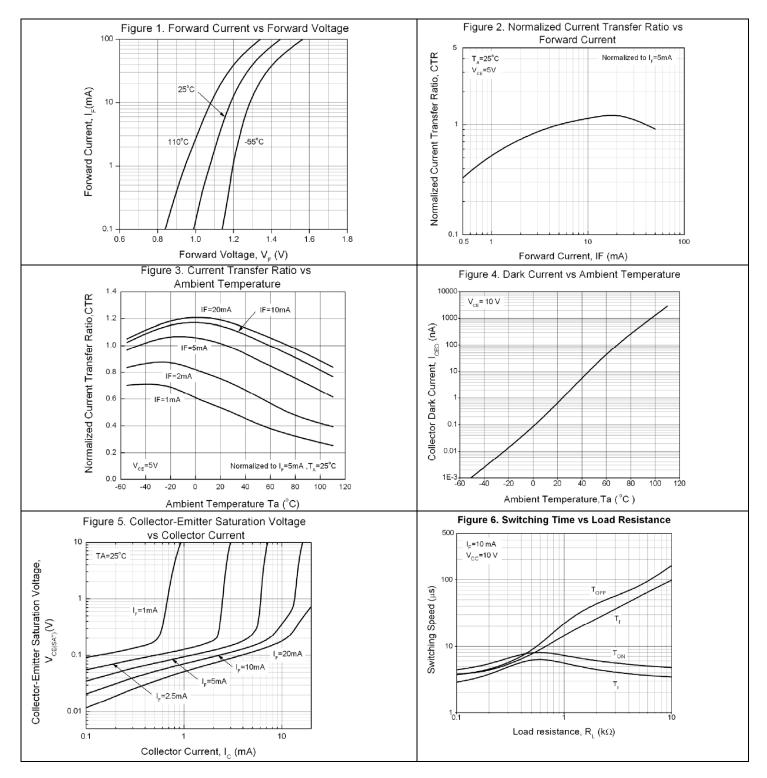
Symbol	Characteristic	Device	Bin	Test Condition	F	Range		Unit
Symbol	Characteristic	Device	DILI	Test Condition	Min	Тур	Max	Unit
R _{ISO}	Isolation			V _{IO} =500Vdc,	5X10 ¹⁰	_	_	Ω
riso	Resistance			40-60% R.H	5710	-	-	12
CISO	Isolation			V _{IO} =0, f = 1MHz	_	0.6	1.0	рF
CISO	Capacitance				-	0.0	1.0	ρг
V	Isolation			f=60Hz, t=1min,	5000			V rms
V _{ISO}	Voltage			I _{I-O} ≤ 2 μA	5000	-	-	v 1115

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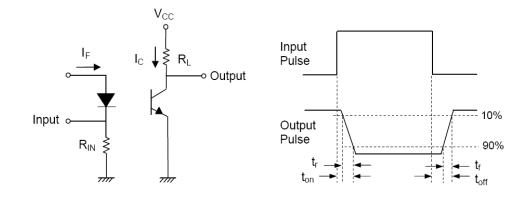
Characteristic Curves:



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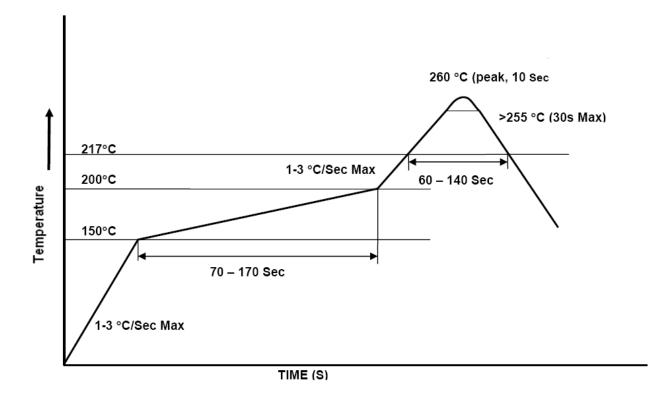
Test Circuit for Response Time:

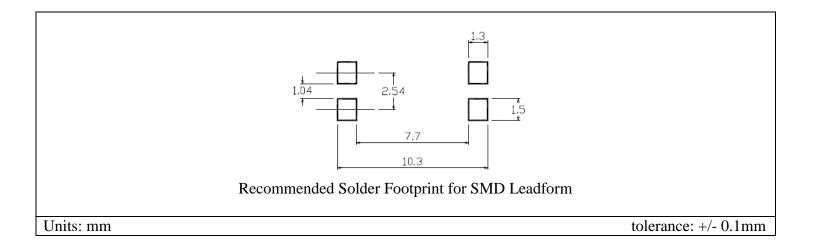


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Solder Profile & Footprint:

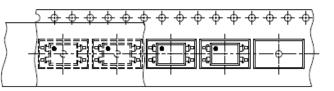


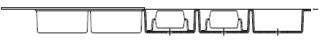


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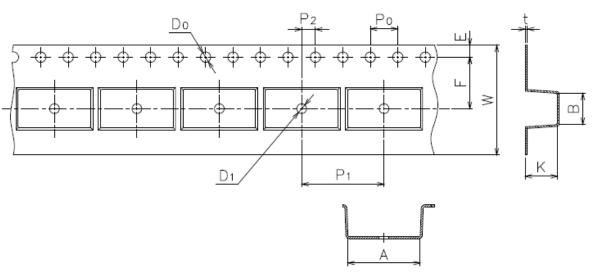


Packing & Labeling: Tape Dimension:





Direction of feed from reel

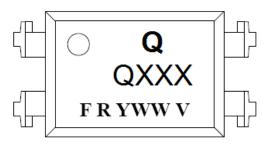


Dimension No.	A	в	Do	D1	E	F
Dimension(mm)	10.4±0.1	4.55±0.1	1.5±0.1	1.5±0.05	1.75±0.1	7.5±0.1
Dimension No.	Po	P1	P2	t	w	к
Dimension(mm)	4.0±0.1	12.0±0.1	2.0±0.1	0.33±0.1	16.0+0.3/ -0.1	4.55±0.1

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Device Marking:



Q = QT-Brightek Corporation QXXX = Device Part NumberF = Country of OriginR = Binning OptionY = YearWW = WeekV = VDE Option

Ordering Information:

Part	Orderable Part	Options	Description	Quantity per
Number	Number			packing
	Q817X	None	Standard 4pin DIP	100pcs / Tube
	Q817XV	None	Standard 4 pin Dip + With VDE marking	100pcs / Tube
	Q817XW	W	Wide lead bend (0.4 inch spacing)	100pcs / Tube
Q817	Q817XWV	W	Wide lead bend (0.4 inch spacing) + VDE marking	100pcs / Tube
	Q817XSTA	S	SMD lead form with tape and reel option	2000pcs / reel
	Q817XSTAV	S	SMD lead form with tape and reel option + VDE marking	2000pcs / reel

X – Note is CTR Binning.

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Revision History:

Description:	Revision #	Revision Date
Initial release	1.0	4/12/2010
Add CTR rank binning option and VDE number	1.1	7/28/2010
Feature, certification & compliance and ordering information updates	1.2	02/01/2011

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1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.

2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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